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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HIROSHI SHIHO, ET AL. : ATTN: APPLICATION DIVISION
SERIAL NO: 10/529,742 :
FILED: MARCH 29, 2005 :
FOR: POLISHING PAD FOR :
SEMICONDUCTOR WAFER AND
LAMINATED BODY FOR
POLISHING OF SEMICONDUCTOR
WAFER EQUIPPED WITH THE
SAME AS WELL AS METHOD FOR
POLISHING OF SEMICONDUCTOR
WAFER

PRELIMINARY AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Prior to a first examination on the merits, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.